

10/039,541

IN THE ABSTRACT:

Please replace the following claims for the same-numbered claims in the application:

~~A method and structure for a system level integration of a battery with an integrated circuit chip comprises a solid state battery, or other types of batteries, an integrated circuit chip powered by the battery, and a package connected to the battery and the integrated circuit chip. The package connects to the integrated circuit chip through an interior portion of the package, and the battery overhangs the integrated circuit chip, wherein the integrated circuit chip connects to an upper indent portion of the package, and wherein the battery is larger than the integrated circuit chip. Alternatively, the battery connects to an underside of the package. Also, there may be a stack of batteries used, or multiple integrated circuit chips arranged in a multi-chip module.~~

A system level device for battery and integrated circuit chip integration comprises at least one battery; at least one integrated circuit chip powered by the at least one battery; and a package connected to any of the at least one battery and the at least one integrated circuit chip, wherein the at least one battery connects to a pair of opposed upright ends of the package, wherein the at least one integrated circuit chip is disposed between the at least one battery and the package, and wherein the at least one integrated circuit chip lays on top of a portion of the package.